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Environmental testing—Part 2-69: Tests—Test Te/Tc: Solderability testing of electronic components and printed boards by the wetting balance (force measurement) method

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Foreword

This Japanese Industrial Standard has been revised by the Minister of Economy, Trade and Industry through deliberations at the Japanese Industrial Standards Committee as the result of proposal for revision of Japanese Industrial Standard submitted by Japan Electronics and Information Technology Industries Association (JEITA)/Japanese Standards Association (JSA) with the draft being attached, based on the provision of Article 12 Clause 1 of the Industrial Standardization Law applicable to the case of revision by the provision of Article 14. Consequently, **JIS C 60068-2-69**:2009 is replaced with this Standard, and **JIS C 60068-2-54**:2009 has been withdrawn and replaced with this Standard.

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JIS C 60068 series consists of the following 55 parts under the general title *Environmental testing*:

- Part 1: General and guidance
- Part 2-1: Tests—Test A: Cold
- Part 2-2: Tests—Test B: Dry heat
- Part 2-6: Tests—Test Fc: Vibration (sinusoidal)
- Part 2-7: Tests—Test Ga and guidance: Acceleration, steady state
- Part 2-11: Tests—Test Ka: Salt mist
- Part 2-13: Tests, Test M: Low air pressure
- Part 2-14: Tests—Test N: Change of temperature
- Part 2-17: Tests—Test Q: Sealing
- Part 2-18: Tests—Test R and guidance: Water
- Part 2-20: Tests—Test T: Test methods for solderability and resistance to soldering heat of devices with leads
- Part 2-21: Tests—Test U: Robustness of terminations and integral mounting devices
- Part 2-27: Tests—Test Ea: Shock
- Part 2-30: Tests—Test Db: Damp heat, cyclic (12 h + +12 h cycle)
- Part 2-31: Tests—Test Ec: Rough handling shocks, primarily for equipment-type specimens
- Part 2-38: Tests—Test Z/AD: Composite temperature/humidity cyclic test
- Part 2-39: Tests—Tests and guidance: Combined temperature or temperature and humidity with low air pressure tests
- Part 2-40: Tests, Test Z/AM: Combined cold/low air pressure tests

- Part 2-41: Tests, Test Z/BM: Combined dry heat/low air pressure tests
- Part 2-42: Tests Test Kc: Sulphur dioxide test for contacts and connections
- Part 2-43: Tests Test Kd: Hydrogen sulphide test for contacts and connections
- Part 2-45: Resistance to solvents (immersion in cleaning solvents)
- Part 2-46: Tests Guidance to Test Kd: Hydrogen sulphide test for contacts and connections
- Part 2-47: Tests—Mounting of specimens for vibration, impact and similar dynamic tests
- Part 2-49: Tests Guidance to Test Kc: Sulphur dioxide test for contacts and connections
- Part 2-52: Tests—Test Kb: Salt mist, cyclic (sodium chloride solution)
- Part 2-53: Tests and guidance—Combined climatic (temperature/humidity) and dynamic (vibration/shock) tests
- Part 2-55: Tests—Test Ee and guidance—Loose cargo testing including bounce
- Part 2-57: Tests—Test Ff: Vibration—Time-history and sine-beat method
- Part 2-58: Tests—Test Td: Test methods for solderability, resistance to dissolution of metallization and to soldering heat of surface mounting devices (SMD)
- Part 2-60: Tests—Test Ke: Flowing mixed gas corrosion test
- Part 2-61: Test methods Test Z/ABDM: Climatic sequence
- Part 2-64: Tests—Test Fh: Vibration, broadband random and guidance
- Part 2-65: Tests—Test Fg: Vibration—Acoustically induced method
- Part 2-66: Test methods—Test Cx: Damp heat, steady state (unsaturated pressurized vapour)
- Part 2-67: Tests—Test Cy: Damp heat, steady state, accelerated test primarily intended for components
- Part 2-68: Dust and sand test
- Part 2-69: Tests—Test Te/Tc: Solderability testing of electronic components and printed boards by the wetting balance (force measurement) method
- Part 2-70: Tests—Test Xb: Abrasion of markings and letterings caused by rubbing of fingers and hands
- Part 2-75: Tests—Test Eh: Hammer tests
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- Part 2-82: Tests—Test XW₁: Whisker test methods for electronic and electric components
- Part 2-83: Tests—Test Tf: Solderability testing of electronic components for surface mounting devices (SMD) by the wetting balance method using solder paste

- Part 3-1: Supporting documentation and guidance-Cold and dry heat tests
- Part 3-2: Background information—Combined temperature/low air pressure tests
- Part 3-3: Guidance Seismic test method for equipments
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- Part 3-5: Supporting documentation and guidance—Confirmation of the performance of temperature chambers
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